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L17: Entry 1 of 1 File: JPAB Oct 23, 1990

PUB-NO: JP402260691A
DOCUMENT-IDENTIFIER: JP 02260691 A
TITLE: FORMATION OF CONDUCTIVE CIRCUIT

PUBN-DATE: October 23, 1990

INVENTOR-INFORMATION:
NAME COUNTRY
HIRAMA, YOSHINORI
ISHIBASHI, TATSUO

ASSIGNEE-INFORMATION:
NAME COUNTRY
NISSHA PRINTING CO LTD

APPL-NO: JP01083257
APPL-DATE: March 31, 1989

INT-CL (IPC): H05K 3/18

ABSTRACT:

PURPOSE: To improve plating nucleuses in uniform dispersion after chemical reduction so as to enable the formation of a fine pattern by a method wherein an organic metal compound or an organic metal complex of a plating nucleus precursor is dispersed into a solution which contains prepolymer.

CONSTITUTION: An organic metal compound or an organic metal complex, a photocuring prepolymer solution, and an organic solvent are mixed to form a photosensitive ink, it is applied onto an insulating board, and a photosensitive ink layer is exposed to light for the formation of a circuit pattern. Not only the non-exposed part of the ink layer is removed by dissolution with a developing solution but also the surface of the exposed part of the ink layer is roughened at the same time. Then, the roughened ink layer is processed with a reluctant to turn the organic metal compound or the organic metal complex dispersed in the ink into plating nucleuses, and a metal layer is formed on the ink layer by dipping the board into electroless plating bath. By this setup, plating nucleuses are high in uniform dispersion, so that a fine pattern can be formed.

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L26: Entry 4 of 15 File: JPAB Sep 24, 1992

PUB-NO: JP404268070A
DOCUMENT-IDENTIFIER: JP 04268070 A
TITLE: FORMATION OF METALLIC LAYER ON SUBSTRATE

PUBN-DATE: September 24, 1992

INVENTOR-INFORMATION:

NAME	COUNTRY
ESROM, HILMAR	

ASSIGNEE-INFORMATION:

NAME	COUNTRY
ABB PATENT GMBH	

APPL-NO: JP03287763
APPL-DATE: November 1, 1991

INT-CL (IPC): C23C 14/28; C23C 14/14; C23C 14/58; C23C 18/31; C25D 5/54

ABSTRACT:

PURPOSE: To provide an economical method for forming a metallic layer on a substrate without exposing the substrate to a solvent.

CONSTITUTION: In this method, An UV transmissive or light transmissive base (1) coated with an organic metallic compound (2) is arranged in front of a substrate (3) at prescribed intervals (A) in such a manner that the organic metallic compound confronts the substrate (3). The organic metallic compound is subjected to the operation of a pulsification photon beam with a prescribed wavelength, preferably, of 190 to 550 nm. In this way, a metallic layer (8) is formed on the substrate from the organic metallic compound. This metallic layer (8) can be reinforced by an electroless method or an electroplating method.

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DATE: Thursday, March 30, 2006

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☐	L24	solut$5 or liquid	6882567
☐	L23	L22 and l20	22
☐	L22	L21 or organ$5	1816655
☐	L21	metalorgan$5 or organmeta$5	4200
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☐	L19	esrom.inv.	67
☐	L18	uv or vuv	298747
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☐	L7	L6 and l5	1
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☐	L5	6524663	4
☐	L4	L3 and l2 and l1	2
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